

## Straight Boardmount Sockets

- 1 – 36 contacts in one row
- Tuning fork contact design
- Gold, tin/lead or pure tin plating
- Standard or high temperature body
- Solder standoffs facilitate production wave soldering
- Optional board retention feature
- Custom versions available

### Physical

#### Insulation

##### Standard Temperature

Material:	Glass filled Polyester (PBT)
Flammability:	UL 94 V-0
Color:	Black

##### High Temperature

Material:	High Temperature Nylon
Flammability:	UL 94 V-0
Color:	Black

#### Contact

Material:	Copper Alloy
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#### Plating Options

##### 0,25µm- Gold (Selective)

Underplating:	1,27µm (50µ") Ni
Wiping Area:	0,25µm (10µ") Au
Solder Tails:	0,25 Sn100 (matt finish) (alternat. SnPb)

##### 0,76µm Gold (Selective)

Underplating:	1,27µm (50µ") Ni
Wiping Area:	0,76µm (30µ") Au
Solder Tails:	2,54µm (100µ") Sn100 matt finish (alternat. SnPb)

#### Tin Lead

Underplating:	1,27µm (50µ") Ni
Wiping Area:	2,54µm (100µ") SnPb
Solder Tails:	2,54µm (100µ") SnPb

#### Tin (Lead free)

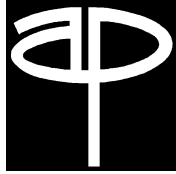
Underplating:	1,27µm (50µ") Ni
Wiping Area:	2,54µm (100µ") Sn100 (matt finish)
Solder Tails:	2,54µm (100µ") Sn100 (matt finish)

### Electrical

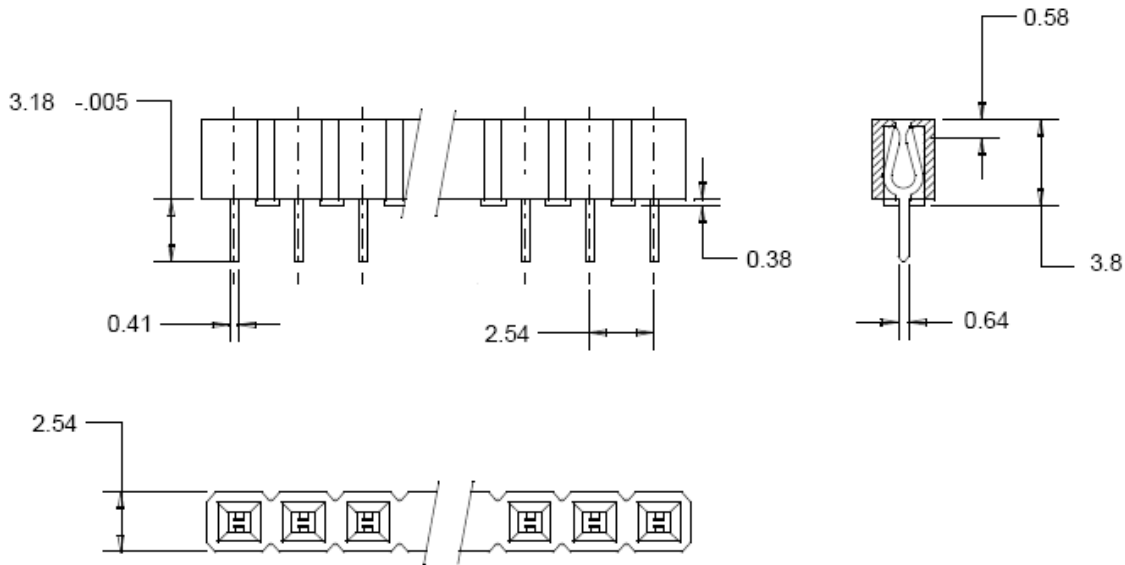
Current Rating:	1 A
Insulation Resistance:	$> 5 \times 10^9 \Omega$ at 500V DC
Withstanding Voltage:	1000 V DC at sea level

### Environmental

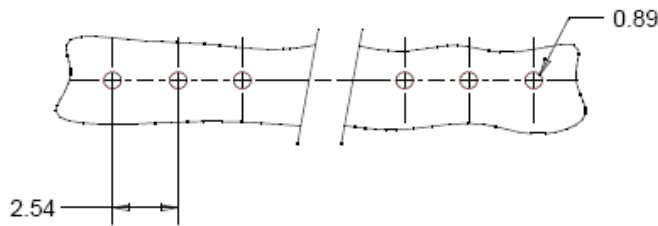
Temperature Rating:	-40 °C to +105 °C	(Standard Temperature)
	-40 °C to +230 °C	(High Temperature)



# Series 093P



### Recommended Mounting Hole Pattern:



## Ordering Information

### 9x9xxx-01-xx-xx

**Product Option:**

- 2 = Standard Product without Kinked Tail
- R = Standard Product with Kinked Tail as Board Retention Feature
- 3 = High Temperature Product without Kinked Tail
- K = High Temperature Product with Kinked Tail as Board Retention Feature

**1 Row Plating options:**

- 870 = Selective Gold / Solder plating
- 984 = Solder plating all over

**Contact Quantity per Row**

- 1 to 36

**Plating Suffix**

- none = full SnPb solder plating
- 10 = min 0,25 µm Au Plating with SnPb Solder Tails
- 15 = 0,25 µm sel. Au Plating with Sn100 Solder Tails
- 30 = min 0,76 µm Au Plating with SnPb Solder Tails
- 35 = 0,76 µm Sel. Au Plating with Sn100 Solder Tails
- 50 = Sn100 Solder Plating

**Engineering Note:**

The information presented in this datasheet is accurate to the best of our knowledge. Due to ongoing efforts to advance design and material performance, this information is subject to change without notice.